

Parameter	Value
V_{CEO}	11V
I_C	50mA

●Features

- 1)High transition frequency.(Typ. $f_T=3.2\text{GHz}$)
- 2)Small $r_{bb'} \cdot C_c$ and high gain.(Typ.4ps)
- 3)Small NF

●Application

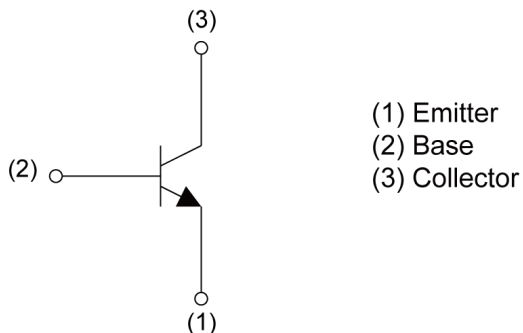
UHF/VHF FREQUENCY CONVERTER, LOCAL OSCILLATOR

●Outline

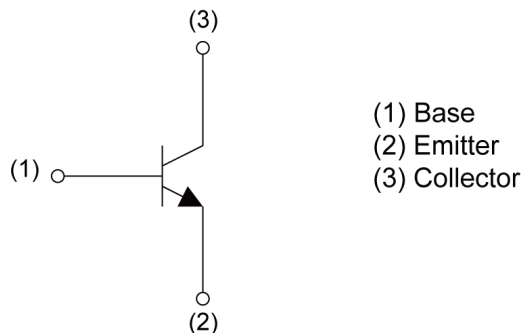
VMT3 2SC5662 SC-105AA	EMT3 2SC4726 SOT-416
UMT3 2SC4083 SOT-323	SMT3 2SC3838K SOT-346

●Inner circuit

2SC4726/2SC4083/2SC3838K



2SC5662



●Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	hFE rank	Marking
2SC5662	VMT3	1212	T2L	180	8	8000	NP	AD
2SC4726	EMT3	1616	TL	180	8	3000	NP	AD
2SC4083	UMT3	2021	T106	180	8	3000	NPQ	1D
2SC3838K	SMT3	2928	T146	180	8	3000	NPQ	AD

●Notice

This product might cause chip aging and breakdown under the large electrified environment.
Please consider to design ESD protection circuit.

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$)

Parameter		Symbol	Values	Unit
Collector-base voltage		V_{CBO}	20	V
Collector-emitter voltage		V_{CEO}	11	V
Emitter-base voltage		V_{EBO}	3	V
Collector current		I_{C}	50	mA
Power dissipation	2SC5662	P_{D}^{*1}	150	mW
	2SC4726		150	
	2SC4083		200	
	2SC3838K		200	
Junction temperature		T_{j}	150	$^\circ\text{C}$
Range of storage temperature		T_{stg}	-55 to +150	$^\circ\text{C}$

●Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Collector-base breakdown voltage	BV_{CBO}	$I_{\text{C}} = 10\mu\text{A}$	20	-	-	V
Collector-emitter breakdown voltage	BV_{CEO}	$I_{\text{C}} = 1\text{mA}$	11	-	-	V
Emitter-base breakdown voltage	BV_{EBO}	$I_{\text{E}} = 10\mu\text{A}$	3	-	-	V
Collector cut-off current	I_{CBO}	$V_{\text{CB}} = 10\text{V}$	-	-	500	nA
Emitter cut-off current	I_{EBO}	$V_{\text{EB}} = 2\text{V}$	-	-	500	nA
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	$I_{\text{C}} = 10\text{mA}$, $I_{\text{B}} = 5\text{mA}$	-	-	500	mV
DC current gain	h_{FE}	$V_{\text{CE}} = 10\text{V}$, $I_{\text{C}} = 5\text{mA}$	56	-	270	-
Transition frequency	f_{T}	$V_{\text{CE}} = 10\text{V}$, $I_{\text{E}} = -10\text{mA}$, $f = 500\text{MHz}$	1.4	3.2	-	GHz
Output capacitance	C_{ob}	$V_{\text{CB}} = 10\text{V}$, $I_{\text{E}} = 0\text{A}$, $f = 1\text{MHz}$	-	0.8	1.5	pF
Noise figure	N_{F}	$V_{\text{CB}} = 6\text{V}$, $I_{\text{C}} = 2\text{mA}$, $f = 500\text{MHz}$, $R_{\text{g}} = 50\Omega$	-	3.5	-	dB

h_{FE} values are classified as follows :

rank	N	P	Q	-	-
h_{FE}	56-120	82-180	120-270	-	-

*1 Each terminal mounted on a reference land.

●Electrical characteristic curves($T_a = 25^\circ\text{C}$)

Fig.1 Ground Emitter Propagation Characteristics

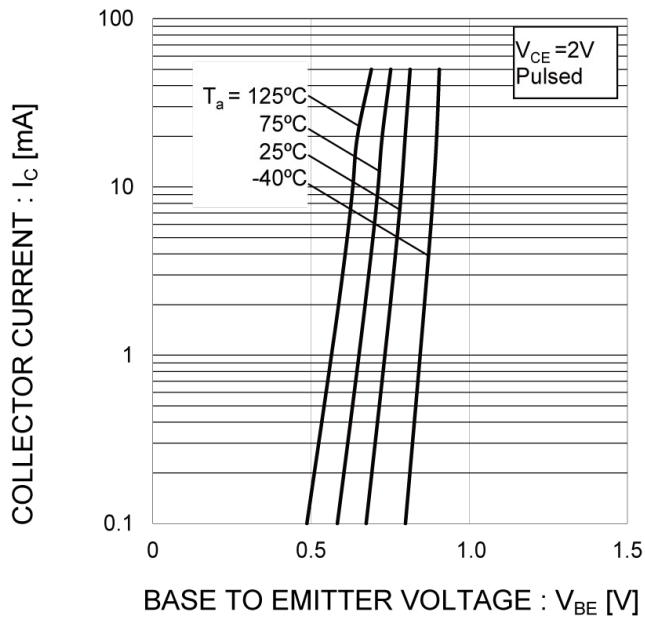


Fig.2 Typical Output Characteristics

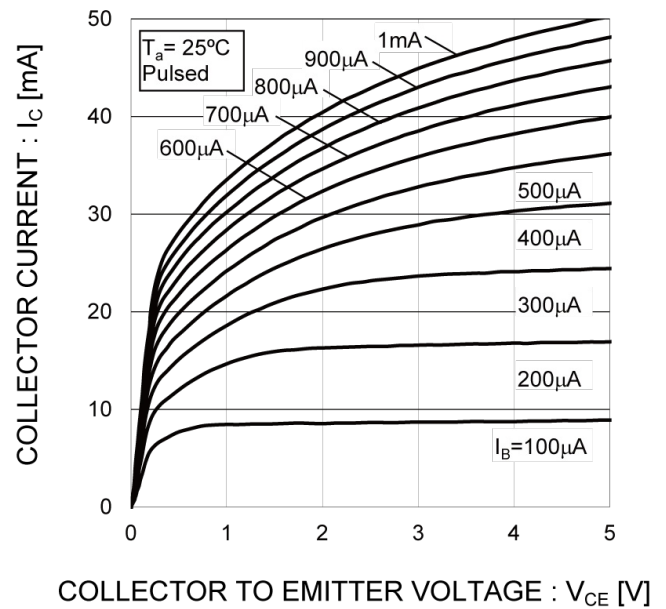


Fig.3 DC Current Gain vs. Collector Current (I)

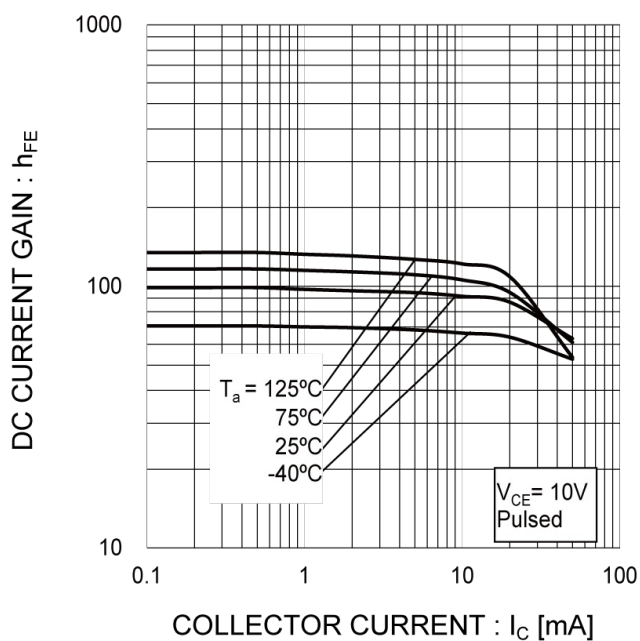
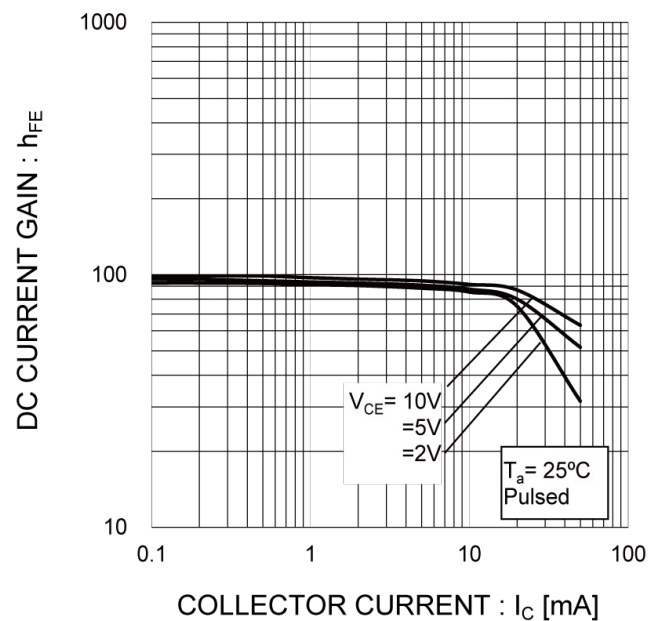


Fig.4 DC Current Gain vs. Collector Current (II)



●Electrical characteristic curves($T_a = 25^\circ\text{C}$)

Fig.5 Collector-Emitter Saturation
Voltage vs. Collector Current (I)

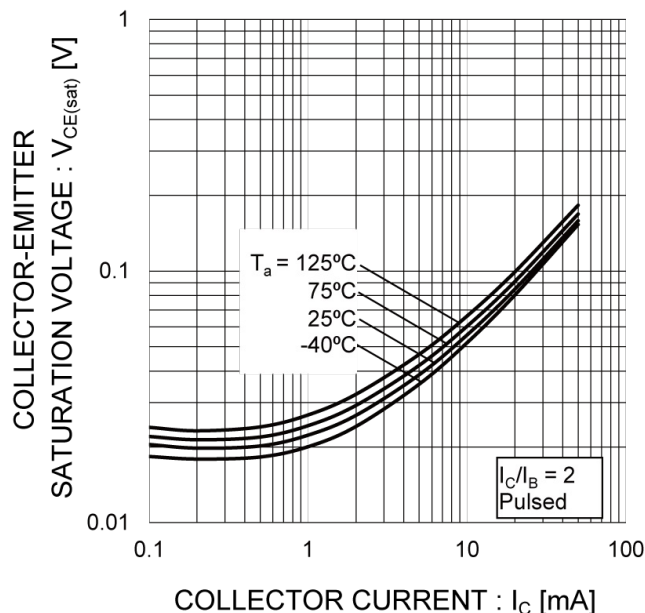


Fig.6 Collector-Emitter Saturation
Voltage vs. Collector Current (II)

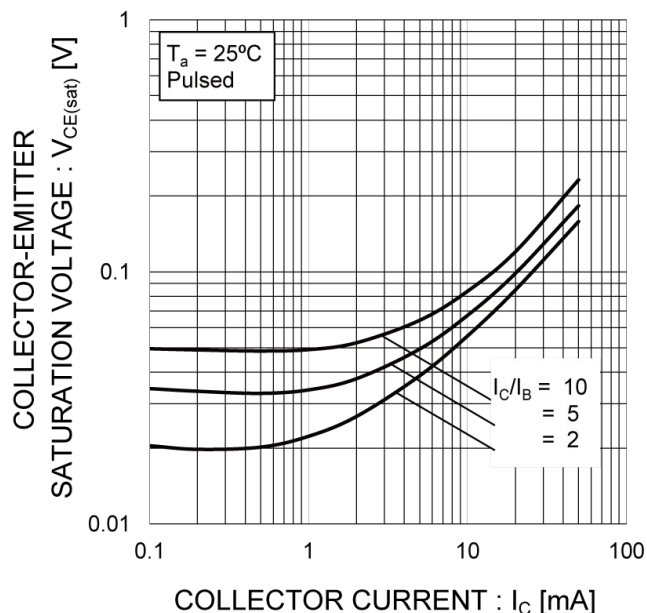


Fig.7 Base-Emitter Saturation Voltage
vs. Collector Current

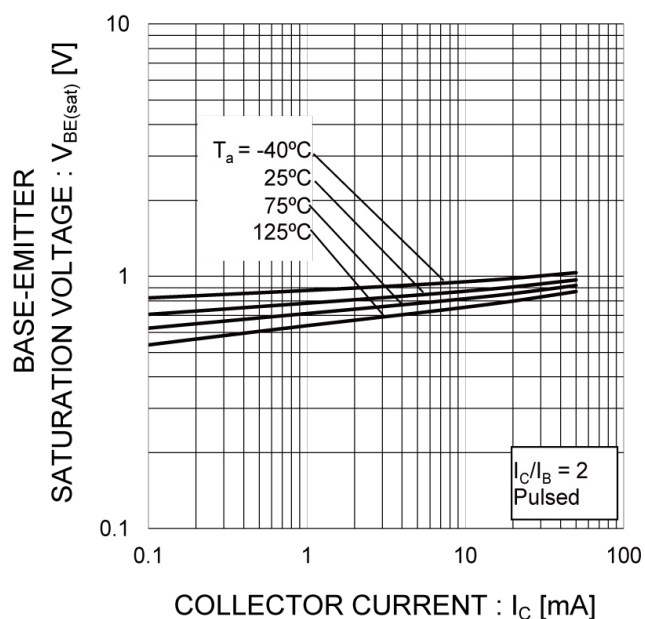
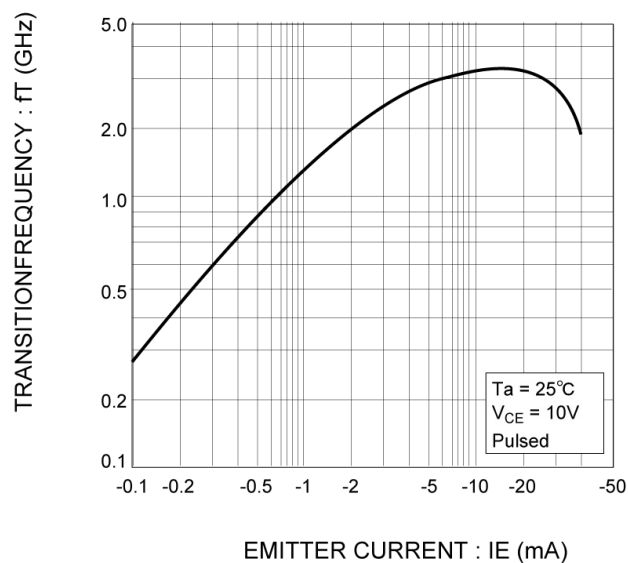


Fig.8 Gain Bandwidth Product vs.
Emitter Current



●Electrical characteristic curves($T_a = 25^\circ\text{C}$)

Fig.9 Capacitance vs. Reverse Bias Voltage

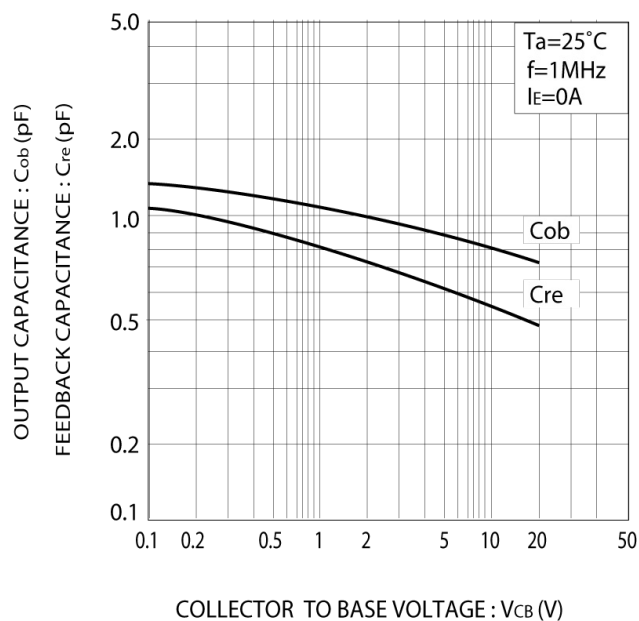


Fig.10 Collector to base time constant vs. collector current

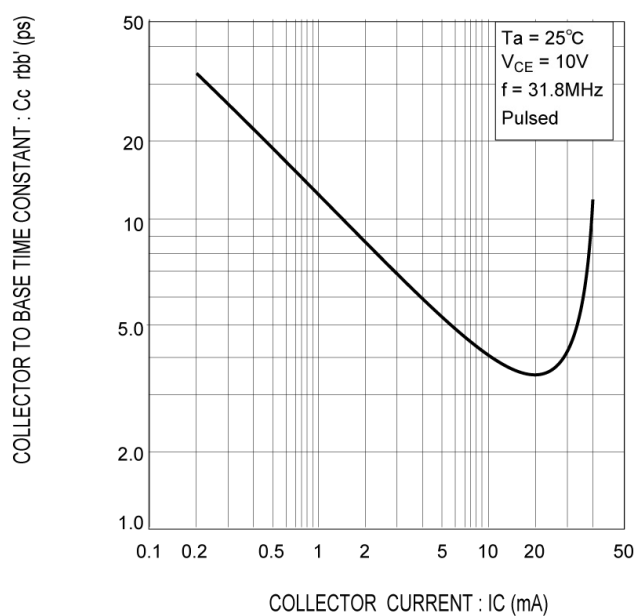
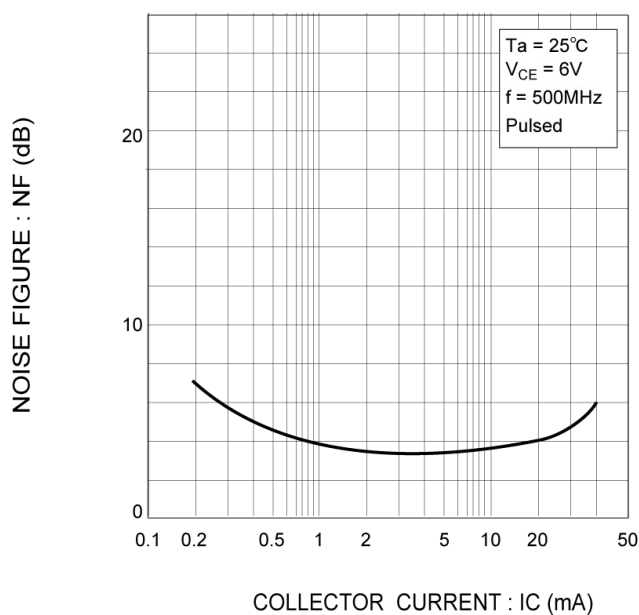
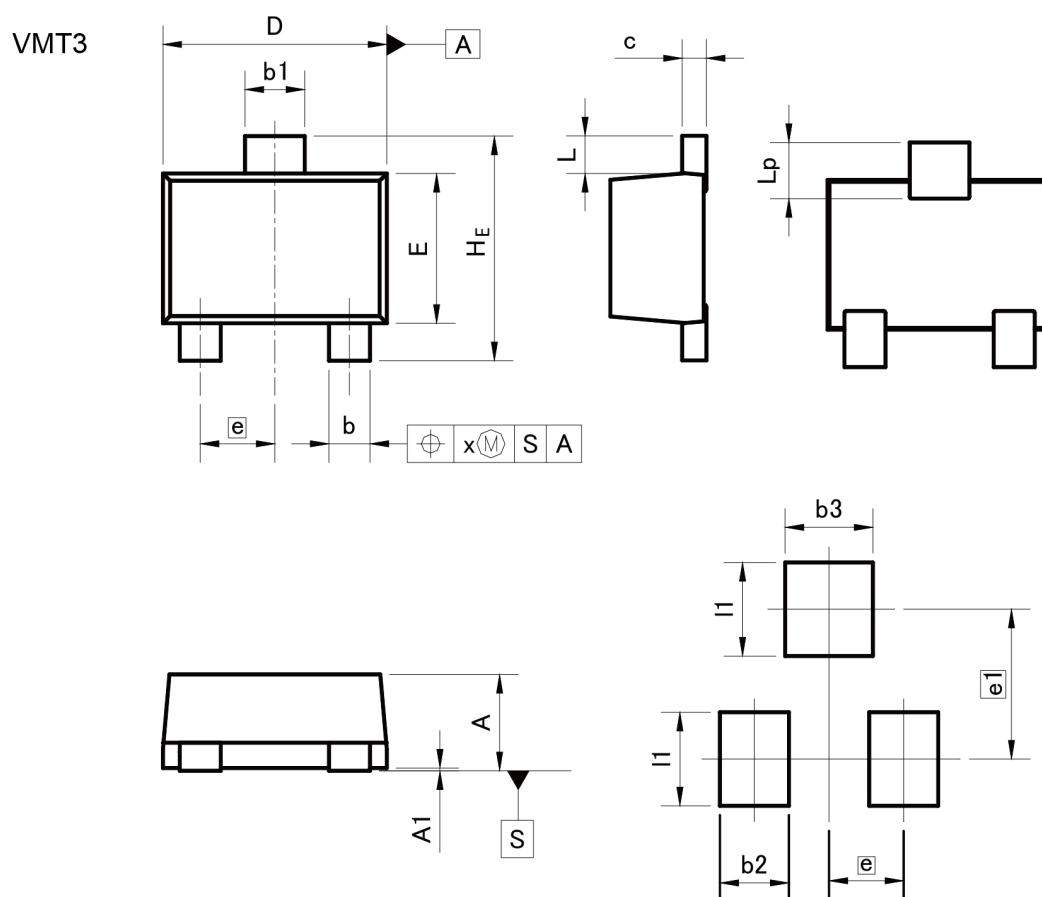


Fig.11 Noise factor vs. collector current characteristics



●Dimensions



Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

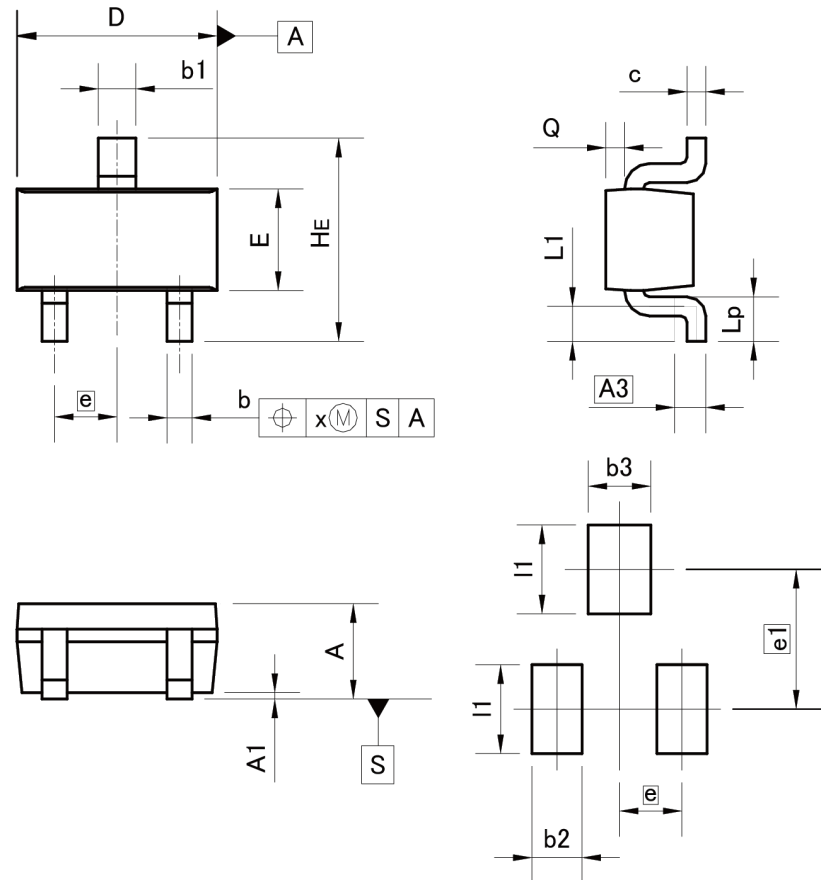
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
c	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
e	0.40		0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
x	—	0.10	—	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	—	0.37	—	0.015
b3	—	0.47	—	0.019
e1	0.80		0.031	
l1	—	0.50	—	0.020

Dimension in mm/inches

●Dimensions

EMT3



Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

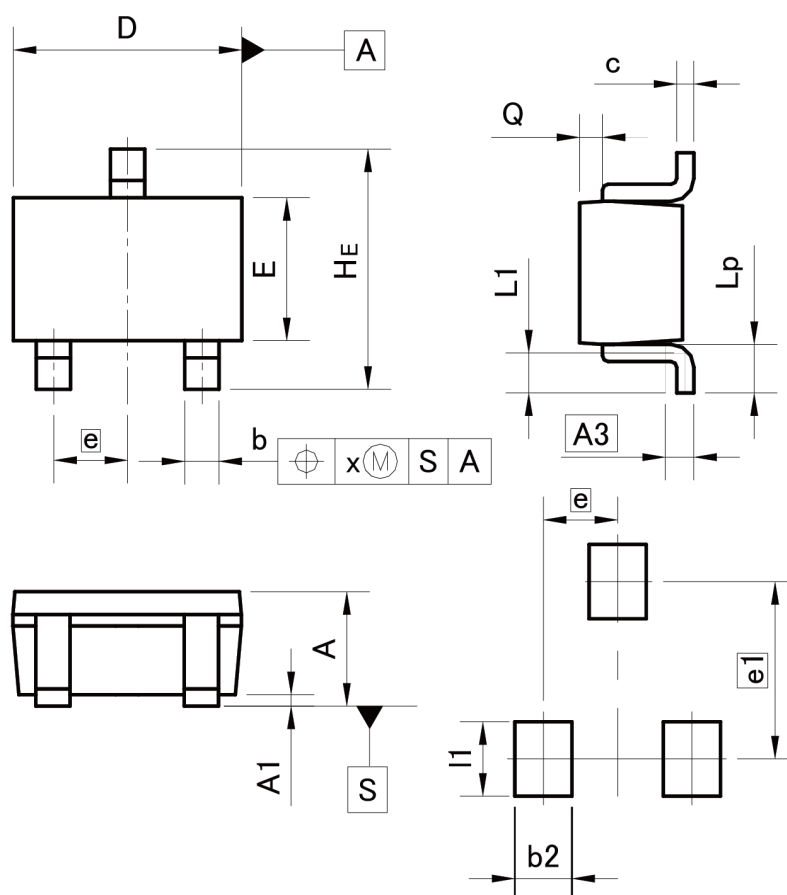
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
e	0.50		0.020	
HE	1.40	1.80	0.055	0.071
L1	0.10	—	0.004	—
Lp	0.15	—	0.006	—
Q	0.05	0.25	0.002	0.010
x	—	0.10	—	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	—	0.40	—	0.016
b3	—	0.50	—	0.020
e1	1.10		0.043	
l1	—	0.70	—	0.028

Dimension in mm/inches

●Dimensions

UMT3



Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

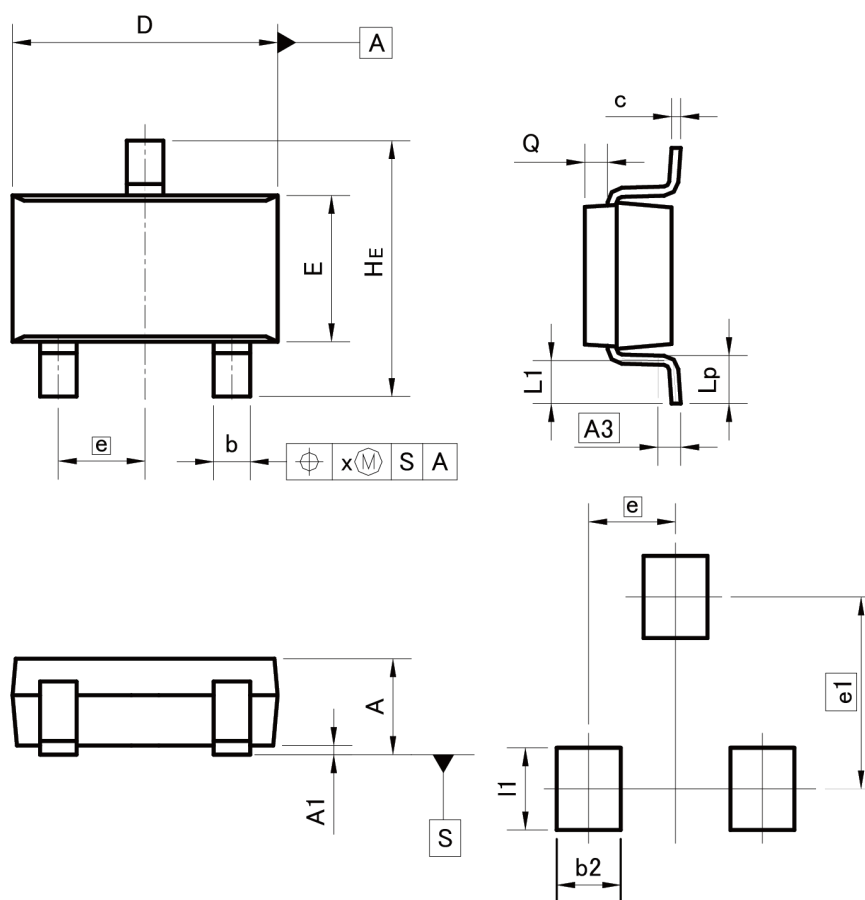
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
c	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	—	0.10	—	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	—	0.50	—	0.020
e1	1.55		0.061	
l1	—	0.65	—	0.026

Dimension in mm/inches

●Dimensions

SMT3



Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
c	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	—	0.10	—	0.004
y	—	0.10	—	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	—	0.60	—	0.024
e1	2.10		0.083	
l1	—	0.90	—	0.035

Dimension in mm/inches

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